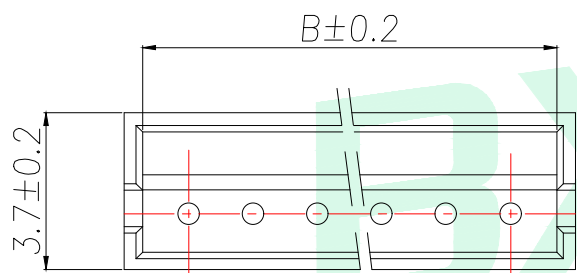
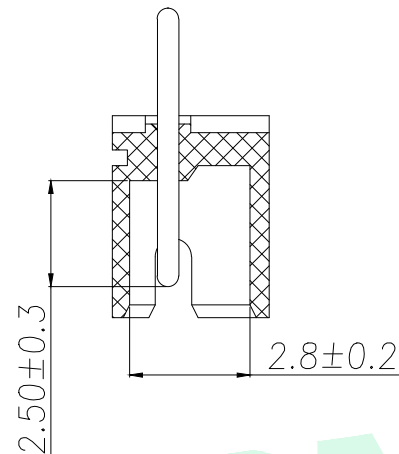
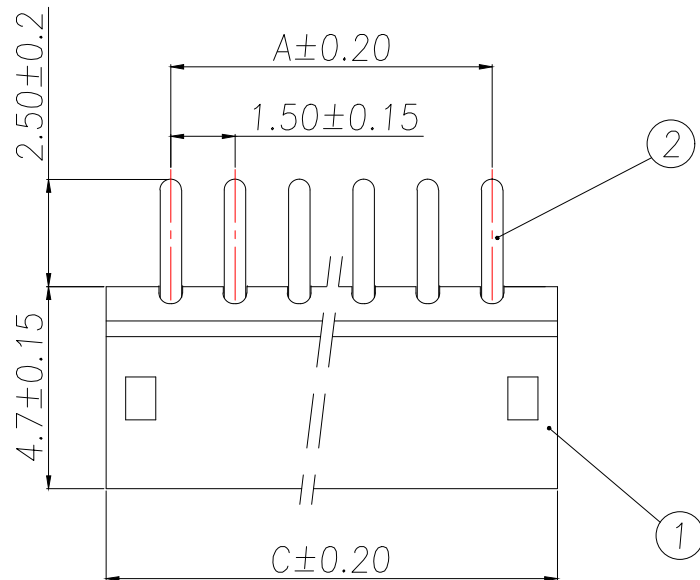
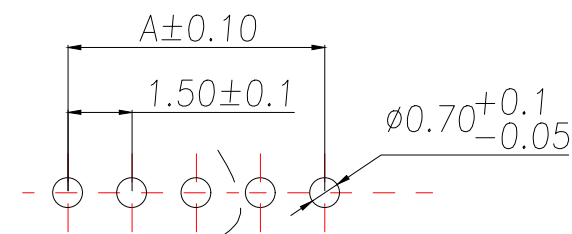


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REV.	DESCRIPTION	ECN NO.	NAME	DATE	



技术要求:

1. 塑件材料:PA66(UL-94V-0)
2. 接触件:黄铜镀锡
3. 接触电阻: $\leq 10\text{m}\Omega$
4. 绝缘电阻: $\geq 100\text{M}\Omega$
5. 额定电压:250V AC DC
6. 额定电流:2.0A AC DC
7. 耐压:能承受1000V AC/Minute
8. 工作温度: $-40^{\circ}\sim +85^{\circ}$
9. 可焊性试验:浸锡面积 $\geq 95\%$ 温度 $235\pm 5^{\circ}$,时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求.



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

2	端子Contact	黄铜	N*1	电镀(锡):整个表面镀底镍 30u"MIN,再镀锡80u"MIN
1	基座Wafer	PA66 (UL94V-0)	1	白色
序号	名称	材料	数量	备注

GENERAL TOLERANCE		DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD				BXCONN [®]	
DIM. TOL. .X ±0.20 .XX ±0.10 .XXX ±0.05 GENERAL ANGLE: ±2°		TITLE: WAFER ZH1.5MM 直針					
		DWG. NO.: AF-ZH1.5-NPZZ-W1		CHECKED: MAX			
		PART NO.: AF-ZH1.5-NPZZ-W1		DRAWN: ELLA			
		UNIT: mm	SCALE: none	SHEET: 1 of 1	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL